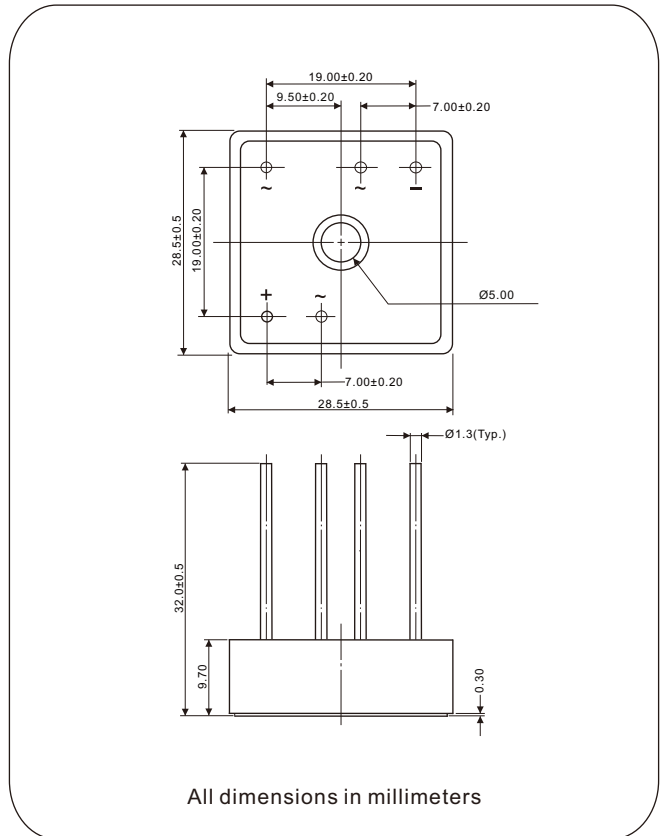


Glass Passivated Triple-Phase Bridge Rectifier, 50A

MTP5006W Thru MTP5016W

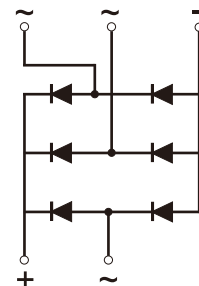


FEATURES

- UL recognition file number E320098
- Universal 3-way terminals: snap-on, wire wrap-around, or PCB mounting
- Typical IR less than $2.0 \mu\text{A}$
- High surge current capability
- Low thermal resistance
- Solder dip 260°C , 40s
- Compliant to RoHS
- Glass passivated chips

TYPICAL APPLICATIONS

General purpose use in AC/DC bridge full wave rectification for big power supply, field supply for DC motor industrial automation applications.



MECHANICAL DATA

- Case:** GBPC
Epoxy meets UL 94 V-O flammability rating
- Terminals:** Nickel plated on wire leads, solderable per J-STD-002 and JESD22-B102.
- Polarity:** As marked
- Mounting Torque:** 20 inches-lbs. max.
- Weight:** 21g (0.74 ozs)

PRIMARY CHARACTERISTICS

$I_{F(AV)}$	50A
V_{RRM}	600V to 1600V
I_{FSM}	500A
I_R	$5 \mu\text{A}$
V_F	1.2V
$T_{Jmax.}$	150°C

MAJOR RATINGS AND CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)							
PARAMETER	SYMBOL	MTP50..W					UNIT
		06	08	10	12	16	
Maximum repetitive peak reverse voltage	V_{RRM}	600	800	1000	1200	1600	V
Maximum RMS voltage	V_{RMS}	420	560	700	840	1120	V
Maximum DC blocking voltage	V_{DC}	600	800	1000	1200	1600	V
Maximum average forward rectified output current (Fig.1)	$I_{F(AV)}$	50					A
Peak forward surge current single sine-wave superimposed on rated load	I_{FSM}	500					A
Rating (non-repetitive, for t greater than 1 ms and less than 8.3 ms) for fusing	I^2t	1000					A ² s
RMS isolation voltage from case to leads	V_{ISO}	2500					V
Operating junction storage temperature range	T_J, T_{STG}	-55 to 150					$^\circ\text{C}$

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)								
PARAMETER	TEST CONDITIONS	SYMBOL	MTP50..W					UNIT
			06	08	10	12	16	
Maximum instantaneous forward drop per diode	$I_F = 25\text{A}$	V_F	1.2					V
Maximum reverse DC current at rated DC blocking voltage per diod	$T_A = 25^\circ\text{C}$	I_R	5					μA
	$T_A = 150^\circ\text{C}$		1000					
Typical junction capacitance per diode	4V, 1MHz	C_J	300					pF

THERMAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)							
PARAMETER	SYMBOL	MTP50..W					UNIT
		06	08	10	12	16	
Typical thermal resistance	$R_{\theta JC}^{(1)}$	1.0					$^\circ\text{C/W}$

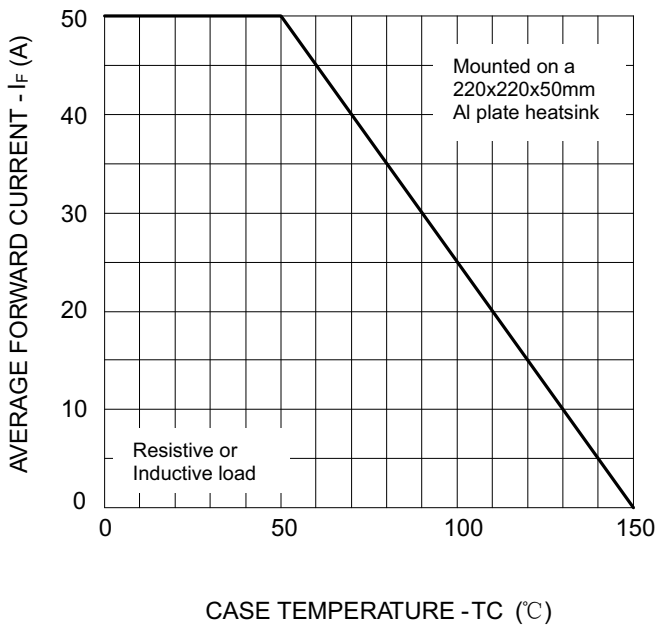
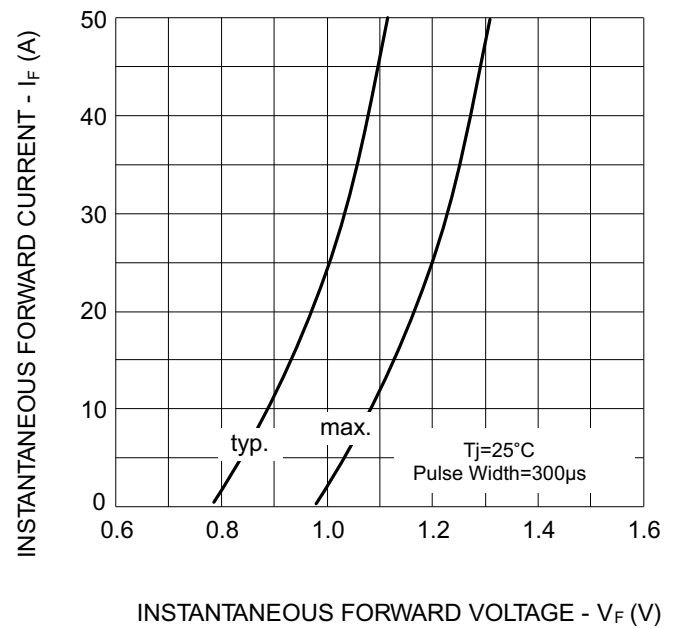
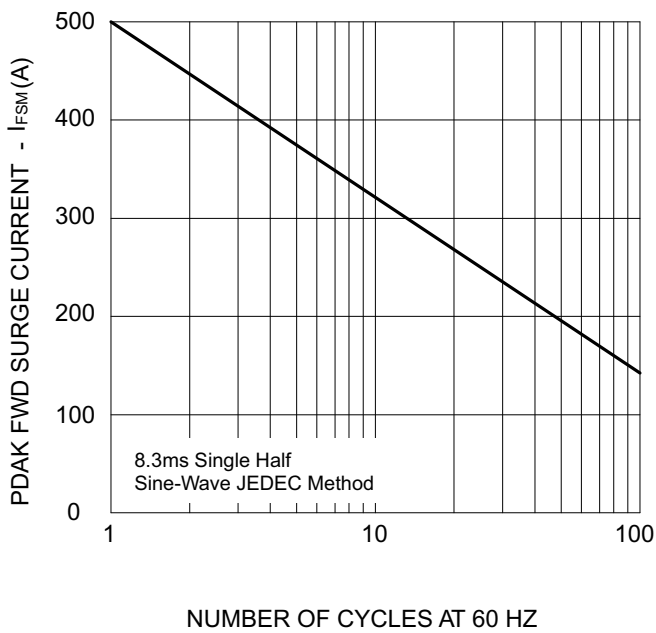
Notes

- (1) With heatsink
- (2) Bolt down on heatsink with silicone thermal compound between bridge and mounting surface for maximum heat transfer with #10 screw

ORDERING INFORMATION TABLE

Device code	MTP	50	16	W
	①	②	③	④

- | | | |
|---|---|---------------------------------------|
| 1 | - | Module type: 3 phase Bridge |
| 2 | - | Current rating: $I_{F(AV)}$ |
| 3 | - | Voltage code x 10: V_{RRM} |
| 4 | - | Package outline: W for "GBPC" package |

Fig.1 Forward Current Derating Curve

Fig.2 Typical Forward Characteristics

Fig.3 Max Non-Repetitive Peak Surge Current

Fig.4 Transient thermal impedance
